

Feature

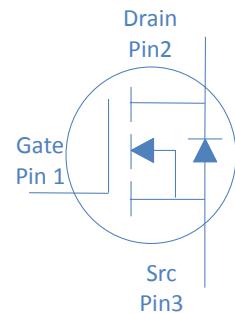
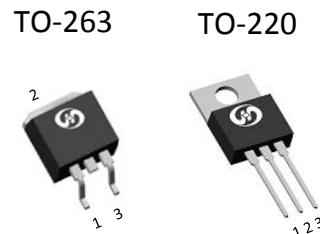
- ◊ High Speed Power Smooth Switching, Logic Level
- ◊ Enhanced Body diode dv/dt capability
- ◊ Enhanced Avalanche Ruggedness
- ◊ 100% UIS Tested, 100% Rg Tested
- ◊ Lead Free

150V N-Ch Power MOSFET

V_{DS}	150	V
$R_{DS(on),typ}$	TO-263	38 mΩ
$R_{DS(on),typ}$	TO-220	41 mΩ
I_D	29	A

Application

- ◊ Synchronous Rectification in SMPS
- ◊ Hard Switching and High Speed Circuit
- ◊ Power Tools
- ◊ UPS
- ◊ Motor Control



Part Number	Package	Marking
HGB480N15M	TO-263	GB480N15M
HGP480N15M	TO-220	GP480N15M

Absolute Maximum Ratings at $T_j=25^\circ\text{C}$ (unless otherwise specified)

Parameter	Symbol	Conditions	Value	Unit
Continuous Drain Current	I_D	$T_C=25^\circ\text{C}$	28.7	A
		$T_C=100^\circ\text{C}$	20.3	
Drain to Source Voltage	V_{DS}	-	150	V
Gate to Source Voltage	V_{GS}	-	± 20	V
Pulsed Drain Current	I_{DM}	-	45	A
Avalanche Energy, Single Pulse	E_{AS}	$L=0.4\text{mH}, T_C=25^\circ\text{C}$	20	mJ
Power Dissipation	P_D	$T_C=25^\circ\text{C}$	88	W
Operating and Storage Temperature	T_J, T_{stg}	-	-55 to 175	°C

Absolute Maximum Ratings

Parameter	Symbol	Max	Unit
Thermal Resistance Junction-Case	R_{eJC}	1.7	°C/W
Thermal Resistance Junction-Ambient	R_{eJA}	65	°C/W

Electrical Characteristics at $T_j=25^\circ\text{C}$ (unless otherwise specified)
Static Characteristics

Parameter	Symbol	Conditions	Value			Unit	
			min	typ	max		
Drain to Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_D=250\mu\text{A}$	150	-	-	V	
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}}=V_{\text{DS}}, I_D=250\mu\text{A}$	2	3	4		
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=150\text{V}, T_j=25^\circ\text{C}$	-	-	1	μA	
		$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=150\text{V}, T_j=100^\circ\text{C}$	-	-	100		
Gate to Source Leakage Current	I_{GSS}	$V_{\text{GS}}=\pm20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	±100	nA	
Drain to Source on Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}}=10\text{V}, I_D=10\text{A}$	TO-263	-	38	48	$\text{m}\Omega$
Drain to Source on Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}}=10\text{V}, I_D=10\text{A}$		-	41	48	$\text{m}\Omega$
Transconductance	g_{fs}	$V_{\text{DS}}=5\text{V}, I_D=10\text{A}$	-	16	-	S	
Gate Resistance	R_G	$V_{\text{GS}}=0\text{V}, V_{\text{DS}} \text{ Open}, f=1\text{MHz}$	-	5.9	-	Ω	

Dynamic Characteristics

Input Capacitance	C_{iss}	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=75\text{V}, f=1\text{MHz}$	-	500	-	pF
Output Capacitance	C_{oss}		-	57	-	
Reverse Transfer Capacitance	C_{rss}		-	9.9	-	
Total Gate Charge	$Q_g \text{ (10V)}$	$V_{\text{DD}}=75\text{V}, I_D=10\text{A}, V_{\text{GS}}=10\text{V}$	-	10	-	nC
Gate to Source Charge	Q_{gs}		-	3.2	-	
Gate to Drain (Miller) Charge	Q_{gd}		-	3.8	-	
Turn on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}}=75\text{V}, I_D=10\text{A}, V_{\text{GS}}=10\text{V}$, $R_G=10\Omega$,	-	11	-	ns
Rise time	t_r		-	7	-	
Turn off Delay Time	$t_{\text{d}(\text{off})}$		-	12	-	
Fall Time	t_f		-	3	-	

Reverse Diode Characteristics

Diode Forward Voltage	V_{SD}	$V_{\text{GS}}=0\text{V}, I_F=20\text{A}$	-	0.9	1.2	V
Reverse Recovery Time	t_{rr}	$V_R=75\text{V}, I_F=10\text{A}, dI_F/dt=100\text{A}/\mu\text{s}$	-	64	-	ns
Reverse Recovery Charge	Q_{rr}		-	96	-	nC

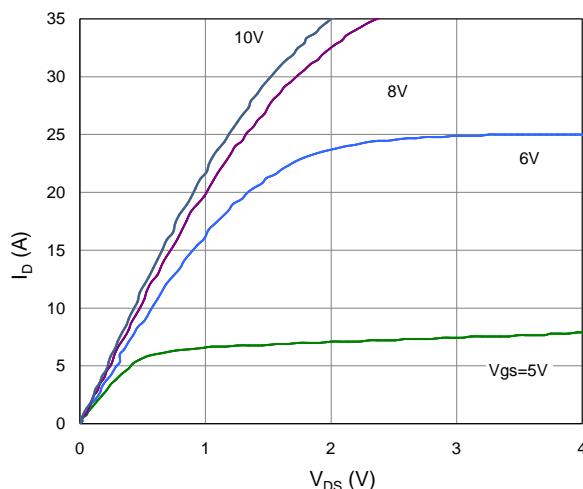
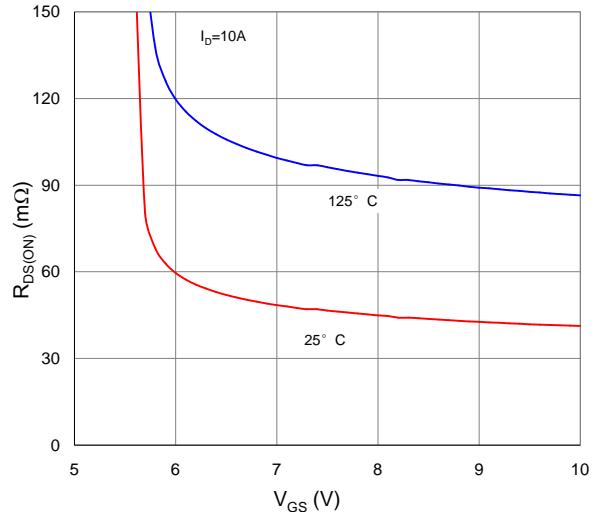
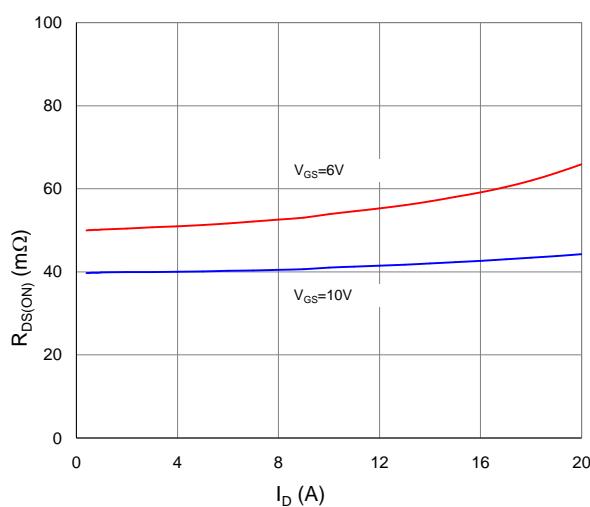
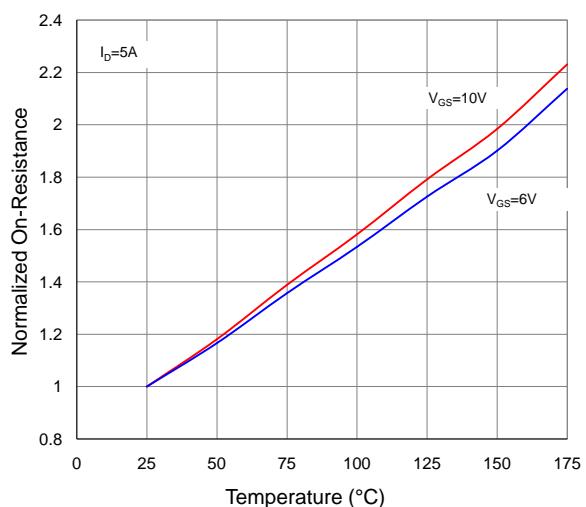
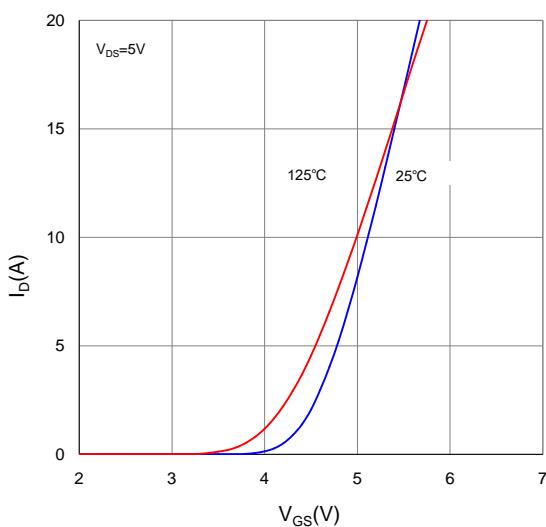
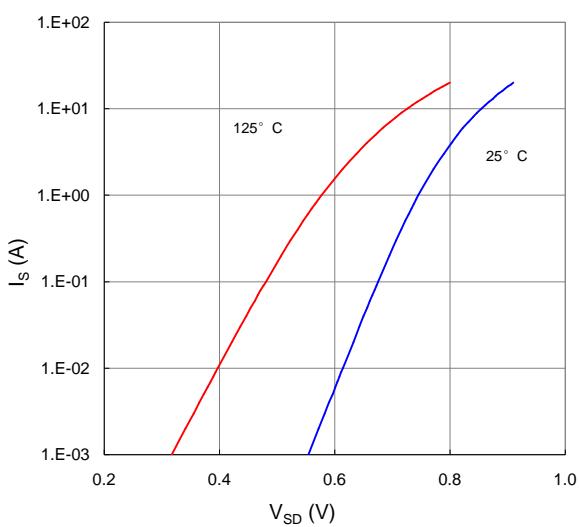
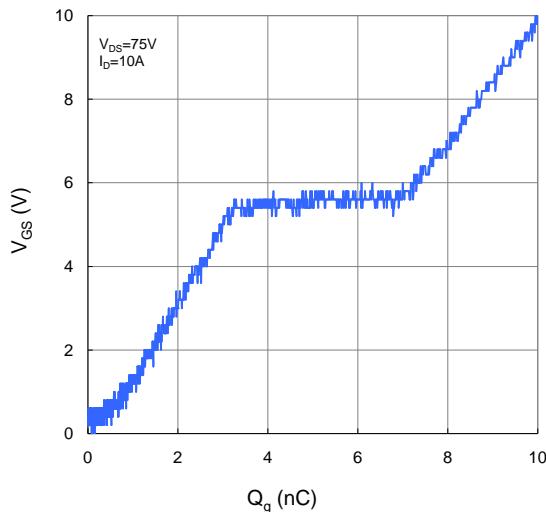
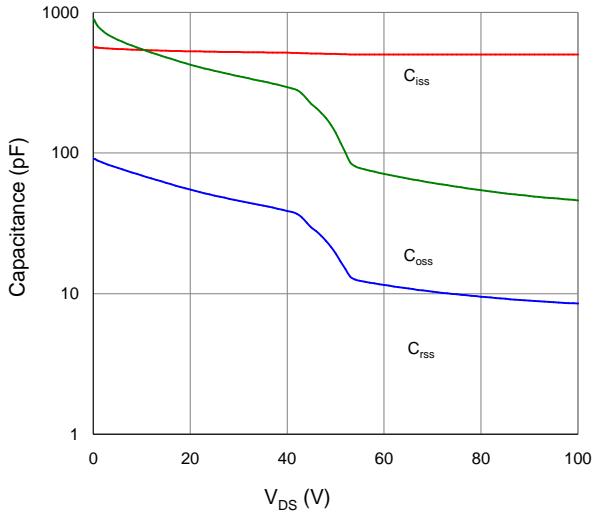
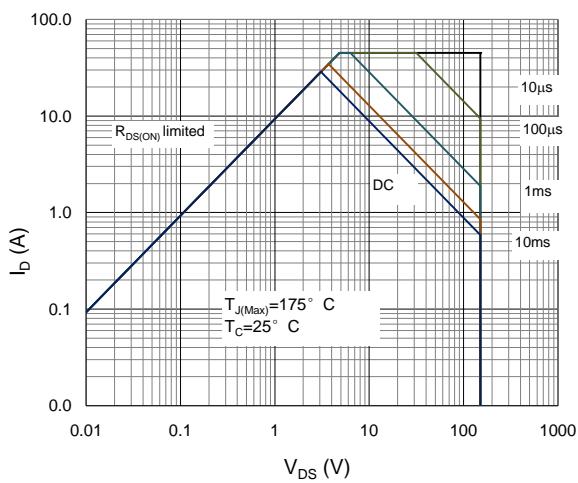
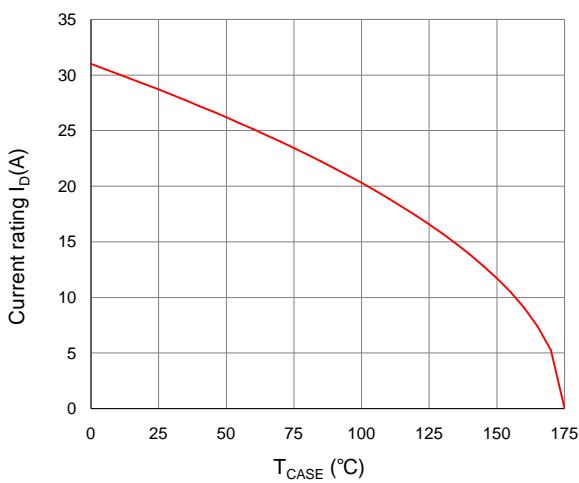
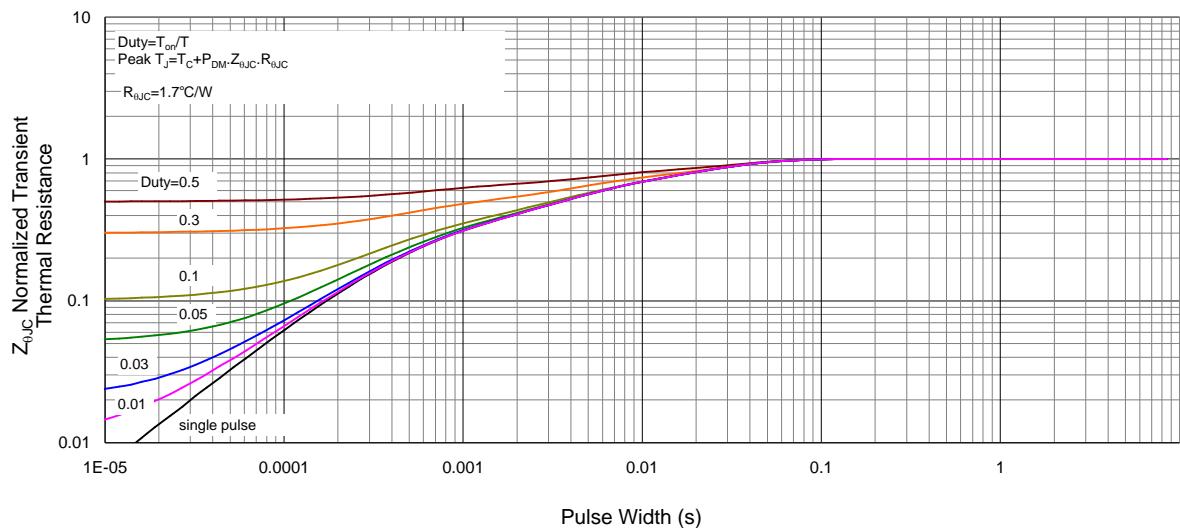
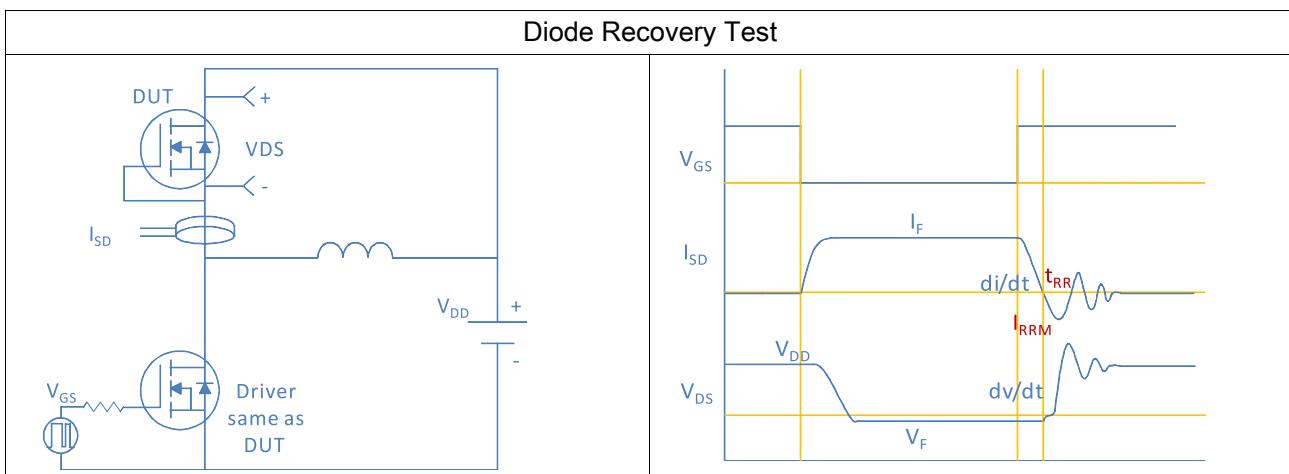
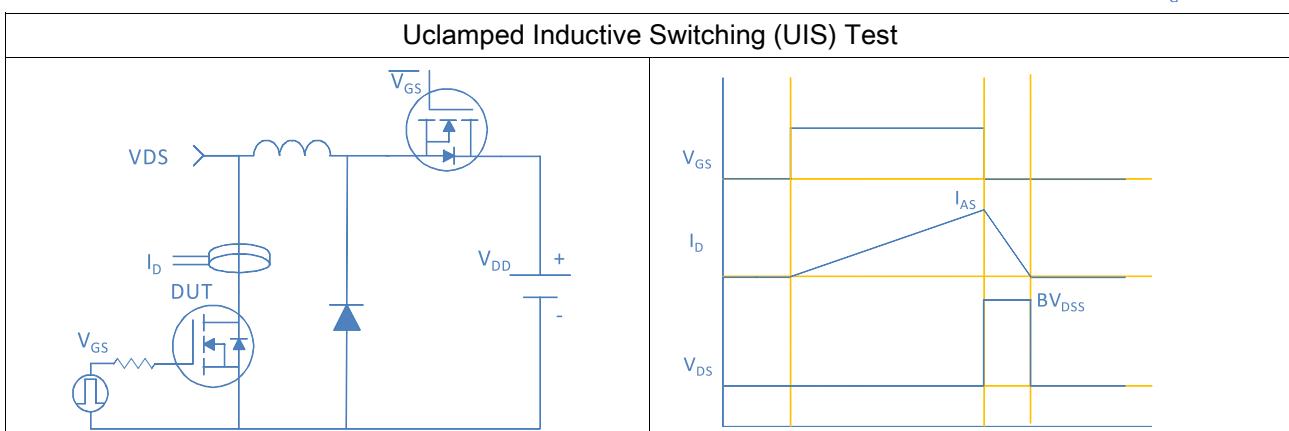
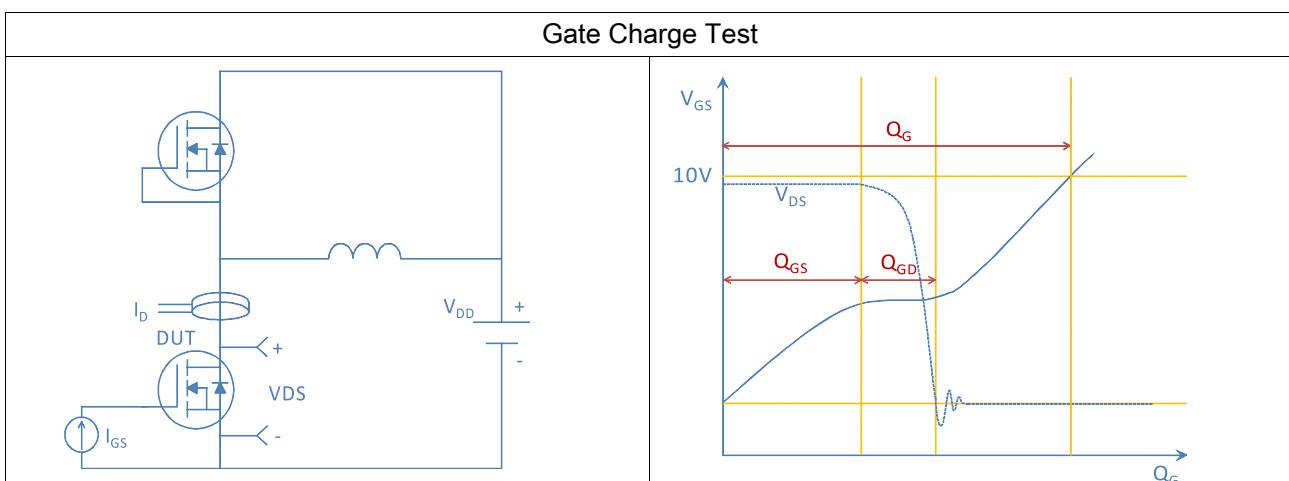
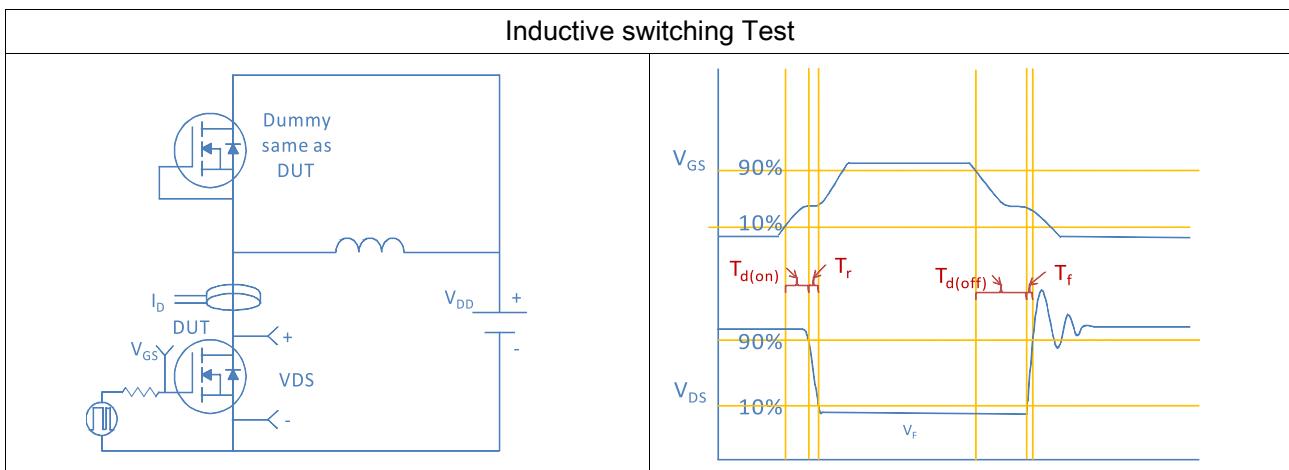
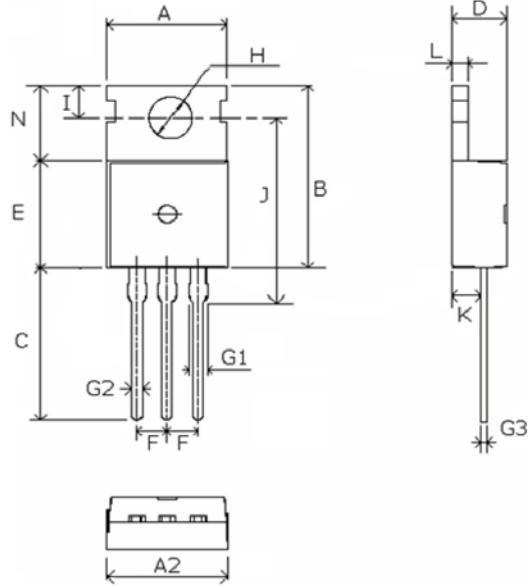
Fig 1. Typical Output Characteristics

Figure 2. On-Resistance vs. Gate-Source Voltage

Figure 3. On-Resistance vs. Drain Current and Gate Voltage

Figure 4. Normalized On-Resistance vs. Junction Temperature

Figure 5. Typical Transfer Characteristics

Figure 6. Typical Source-Drain Diode Forward Voltage


Figure 7. Typical Gate-Charge vs. Gate-to-Source Voltage

Figure 8. Typical Capacitance vs. Drain-to-Source Voltage

Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature

Figure 11. Normalized Maximum Transient Thermal Impedance, Junction-to-Case




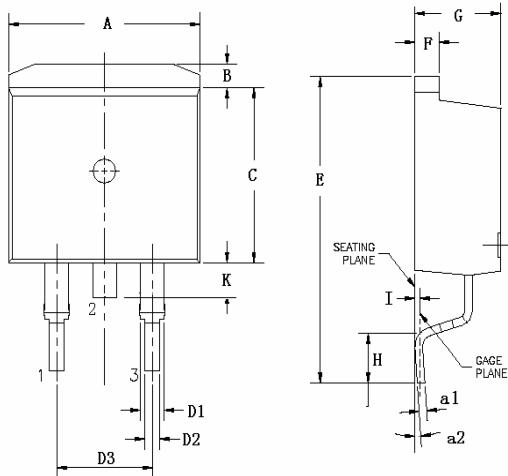

TO-220, 3 leads

Dimensions in mm unless otherwise specified

Symbol	Min	Nom	Max
A	9.66	9.97	10.28
A2	9.80	10.00	10.20
B	15.60	15.70	15.80
C	12.70	13.48	14.27
D	4.30	4.50	4.70
E	9.00	9.20	9.40
F		2.54	
G1	1.32	1.52	1.72
G2	0.70	0.82	0.95
G3	0.45	0.52	0.60
H	3.50	3.60	3.70
I	2.70	2.80	2.90
J	15.70	15.97	16.25
K	2.20	2.40	2.60
L	1.15	1.27	1.40
N	6.40	6.60	6.80

TO-263, 2 leads

Dimensions in mm unless otherwise specified



Symbol	Min	Nom	Max
A	9.66	9.97	10.28
B	1.02	1.17	1.32
C	8.59	9.00	9.40
D1	1.14	1.27	1.40
D2	0.70	0.83	0.95
D3		5.08	
E	15.09	15.24	15.39
F	1.15	1.28	1.40
G	4.30	4.50	4.70
H	2.29	2.54	2.79
I		0.25	
K	1.30	1.45	1.60
a1	0.45	0.55	0.65
a2(degree)	0°		8°